

Materials Declaration

Package	CerDIP
Body Size	300 mils
Lead Count	24
Option	SnPb

Base			
Substance	% of Base	Weight (g)	PPM
Ceramics			
Aluminum Oxide	70.25	1.33 E+00	347496
Manganese Dioxide	2.66	5.05 E-02	13158
Silicon Dioxide	2.30	4.37 E-02	11377
Titanium Dioxide	1.50	2.85 E-02	7420
Chromium Oxide	1.10	2.09 E-02	5441
Iron Oxide	0.90	1.71 E-02	4452
Magnesium Oxide	0.40	7.60 E-03	1979
Cobalt Oxide	0.20	3.80 E-03	989
Calcium Oxide	0.03	5.70 E-04	148
Subtotal	79.34	1.51 E+00	392460
Sealing Glass			
Lead Oxide	12.55	2.38 E-01	62079
Tin Oxide	3.30	6.27 E-02	16324
Silicon Dioxide	1.50	2.85 E-02	7420
Boron Trioxide	1.20	2.28 E-02	5936
Aluminum Oxide	0.80	1.52 E-02	3957
Titanium Dioxide	0.50	9.50 E-03	2473
Magnesium Oxide	0.50	9.50 E-03	2473
Zinc Oxide	0.20	3.80 E-03	989
Calcium Oxide	0.05	9.50 E-04	247
Iron Oxide	0.03	5.70 E-04	148
Chromium Oxide	0.02	3.80 E-04	99
Manganese Dioxide	0.01	1.90 E-04	49
Sodium Oxide	0.002	3.80 E-05	10
Subtotal	20.662	3.93 E-01	102206
Total	100.00	1.90 E+00	494666

Caps			
Substance	% of Caps	Weight (g)	PPM
Ceramics			
Aluminum Oxide	63.90	8.95 E-01	232905
Manganese Dioxide	2.40	3.36 E-02	8748
Silicon Dioxide	2.10	2.94 E-02	7654
Titanium Dioxide	1.30	1.82 E-02	4738
Chromium Oxide	1.00	1.40 E-02	3645
Iron Oxide	0.80	1.12 E-02	2916
Magnesium Oxide	0.40	5.60 E-03	1458
Cobalt Oxide	0.20	2.80 E-03	729
Calcium Oxide	0.03	4.20 E-04	109
Subtotal	72.13	1.01 E+00	262902
Sealing glass			
Lead oxide	17.00	2.38 E-01	61962
Tin oxide	4.50	6.30 E-02	16402
Silicon dioxide	2.03	2.84 E-02	7399
Boron Trioxide	1.60	2.24 E-02	5832
Aluminum oxide	1.10	1.54 E-02	4009
Magnesium oxide	0.60	8.40 E-03	2187
Titanium Dioxide	0.70	9.80 E-03	2551
Calcium oxide	0.06	8.40 E-04	219
Zinc oxide	0.20	2.80 E-03	729
Chromium oxide	0.03	4.20 E-04	109
Iron oxide	0.04	5.60 E-04	146
Manganese dioxide	0.01	1.40 E-04	36
Sodium Oxide	0.003	4.20 E-05	11
Subtotal	27.87	3.90 E-01	101592
Total	100.00	1.40 E+00	364483

Leadframe			
Substance	% of Leadframe	Weight (g)	PPM
Iron	58.45	2.34 E-01	60869
Nickel	40.84	1.63 E-01	42530
Manganese	0.52	2.08 E-03	542
Silicon	0.13	5.20 E-04	135
Cobalt	0.03	1.20 E-04	31
Aluminum	0.01	4.00 E-05	10
Chromium	0.01	4.00 E-05	10
Sulfur	0.01	2.40 E-05	6
Carbon	0.003	1.20 E-05	3
Phosphorus	0.002	8.00 E-06	2
Subtotal	100.00	4.00 E-01	104139

Paste			
Substance	% of Paste	Weight (g)	PPM
Silver	80	3.20 E-03	833
Lead Borate Glass	20	8.00 E-04	208
Subtotal	100	4.00 E-03	1041

Chip			
Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	7.00 E-03	1822

Bonding Wires			
Substance	% of Wire	Weight (g)	PPM
Aluminum	100	1.00 E-01	26035

External Leadframe Plating			
Substance	% of Plating	Weight (g)	PPM
Tin	63	1.89 E-02	4921
Lead	37	1.11 E-02	2892
Subtotal	100	3.00 E-02	7813

Package Totals		
Weight (g)	PPM	
3.84 E+00	1000000	

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability
any inaccuracy of such information.



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